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(8ignature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application of

October 14, 2003

Pogge et al.

Group Art Unit:

Serial No. 10/605,204 :

Examiner:

09-15-03 Filed:

International Business Machines Corporation

2070 Route 52

Hopewell Junction, NY 12533

INTEGRATED ELECTRONIC CHIP AND INTERCONNECT DEVICE AND PROCESS FOR TITLE: MAKING THE SAME

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the non-US patents and publications as listed on Form PTO-1449, are attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or nonpertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,

Anderson

Registration No. 38,371

Telephone No. 845-894-3667

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Docket Number (Optional)

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